BONDING + SEALING + ENCAPSULATION



Insulation / Flame protection

Resin 8601/30S (ex TG 68) + Hardener 8973 (ex 1073)

- 2-components polyurethane casting resin
- solvent-free system
- soft curing degree
- no halogenated flame-retardants
- highly electrically insulating
- excellent adhesive properties
- wide operating temperature range
- suitable for low temperatures applications
- ideal for electronic components, e.g., coils, sensors, PCBs or capacitors

Product specification:

Mixing ratio (weight):	Resin 8601/30S	100 parts	
	Hardener 8973	20 parts	
Viscosity (22°C): (at 10 rpm)	Resin 8601/30S	3'500 − 4'000 mPa·s	
	Hardener 8973	15 − 35 mPa·s	
	Mixing viscosity	1'800 − 2'400 mPa·s	
Density (22°C):	Resin 8601/30S	0.90 - 0.95 g/cm³	
	Hardener 8973	1.20 - 1.25 g/cm³	
Colour:	Black		
Pot life:	25 – 35 minutes		
	The curing time depends on the thickness of the layer, the casting		
	volume and the temperature.		
Curing time (22°C):	16 – 30 hours		
Final hardness	10 - 14 days		

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Physical properties:

Shore-Hardness:	A 25 – 35	ISO 868, DIN 53505
Thermal conductivity:	0.3 W/(m·K)	DIN EN ISO 22007
Glass transition temperature:	-69.1 °C	ТМА
Coefficient of expansion:	101.4 ppm/K	< Tg, TMA
Coefficient of expansion:	222.4 ppm/K	> Tg, TMA
Shrinkage after curing:	<1 %	
Water absorption:	0.2 % (30 days at 23°C)	
Operating temperature:	-80 °C up to +130 °C	
Flammability classification:	HB	

Electrical properties:

Dielectric strength:	25 kV/mm	IEC 60243-1, VDE 0303, TI.2
Volume resistance:	10 ¹⁴ Ω·cm (23°C/ 50% r.F.)	IEC 60243-1, VDE0303, TI.30
Surface resistance:	10 ¹⁶ Ω (23°C/ 50% r.F.)	IEC 60243-1, VDE0303, TI.30
Dielectric constant (ε _r):		
at 50 Hz, 23 °C	3.2	IEC 60250,
at 1 KHz, 23 °C	3.0	VDE 0303, TI.4
at 1 MHz, 23 °C	2.7	
Dissipation factor:		IEC 60250
(tan δ)		IEC 60250,
at 50 Hz, 23 °C	0.02	VDE 0303, TI.4
Comparative Tracking Index:	CTI 600	IEC 60112, VDE 0303, TI.1

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Shelf life:

6 months in sealed original containers when stored in dry conditions (15°C to 25°C).

Packaging:

Resin and hardener are offered in separate packaging units.

Our technical advice, whether verbal, in writing or by way of trials - is given in good faith but without warranty, and this also applies where proprietary rights of third parties are involved. It does not release you from the obligation to test the products supplied by us to their suitability for the intended processes and uses. The application, use and processing of the products are beyond our control and therefore, entirely your own responsibility. Should in spite of this, liability be established by us and used by you. We will, of course, provide products of consistent quality within the scope of our General Conditions of Sale and Delivery.

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